GENERAL DESCRIPTION



The ICS8516 is a low skew, high performance 1-to-16 Differential-to-LVDS Clock Distribution Chip and a member of the HiPerClockS™ family of High Performance Clock Solutions from ICS. The ICS8516 CLK, nCLK pair can accept

any differential input levels and translates them to 3.3V LVDS output levels. Utilizing Low Voltage Differential Signaling (LVDS), the ICS8516 provides a low power, low noise, pointto-point solution for distributing clock signals over controlled impedances of 100Ω .

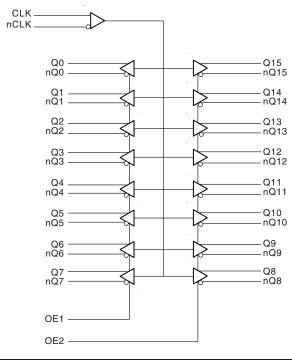
Dual output enable inputs allow the ICS8516 to be used in a 1-to-16 or 1-to-8 input/output mode.

Guaranteed output and part-to-part skew specifications make the ICS8516 ideal for those applications demanding well defined performance and repeatability.

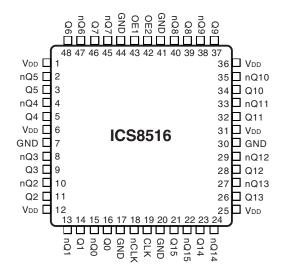
FEATURES

- 16 Differential LVDS outputs
- CLK, nCLK pair can accept the following differential input levels: LVPECL, LVDS, LVHSTL, HCSL, SSTL
- Maximum output frequency: 700MHz
- Translates any differential input signal (LVPECL, LVHSTL, SSTL, DCM) to LVDS levels without external bias networks
- Translates any single-ended input signal to LVDS with resistor bias on nCLK input
- · Multiple output enable inputs for disabling unused outputs in reduced fanout applications
- LVDS compatible
- · Output skew: 90ps (maximum)
- Part-to-part skew: 500ps (maximum)
- Propagation delay: 2.4ns (maximum)
- · 3.3V operating supply
- 0°C to 70°C ambient operating temperature
- Lead-Free package available
- Industrial temperature information available upon request

BLOCK DIAGRAM



PIN ASSIGNMENT



48-Lead LQFP 7mm x 7mm x 1.4mm body package Y Package Top View

Low Skew, 1-to-16 DIFFERENTIAL-TO-LVDS CLOCK DISTRIBUTION CHIP

TABLE 1. PIN DESCRIPTIONS

Number	Name	Т	уре	Description
1, 6, 12, 25, 31, 36	V _{DD}	Power		Positive supply pins.
2, 3	nQ5, Q5	Output		Differential output pair. LVDS interface levels.
4, 5	nQ4, Q4	Output		Differential output pair. LVDS interface levels.
7, 17, 20, 30, 41, 44	GND	Power		Power supply ground.
8, 9	nQ3, Q3	Output		Differential output pair. LVDS interface levels.
10, 11	nQ2, Q2	Output		Differential output pair. LVDS interface levels.
13, 14	nQ1, Q1	Output		Differential output pair. LVDS interface levels.
15, 16	nQ0, Q0	Output		Differential output pair. LVDS interface levels.
18	nCLK	Input	Pullup	Inverting differential clock input.
19	CLK	Input	Pulldown	Non-inverting differential clock input.
21, 22	Q15, nQ15	Output		Differential output pair. LVDS interface levels.
23, 24	Q14, nQ14	Output		Differential output pair. LVDS interface levels.
26, 27	Q13, nQ13	Output		Differential output pair. LVDS interface levels.
28, 29	Q12, nQ12	Output		Differential output pair. LVDS interface levels.
32, 33	Q11, nQ11	Output		Differential output pair. LVDS interface levels.
34, 35	Q10, nQ10	Output		Differential output pair. LVDS interface levels.
37, 38	Q9, nQ9	Output		Differential output pair. LVDS interface levels.
39, 40	Q8, nQ8	Output		Differential output pair. LVDS interface levels.
42, 43	OE2, OE1	Input	Pullup	Output enable. OE2 controls outputs Q8, nQ8 thru Q15, nQ15; OE1 controls outputs Q0, nQ0 thru Q7, nQ7. LVCMOS/LVTTL interface levels.
45, 46	nQ7, Q7	Output		Differential output pair. LVDS interface levels.
47, 48	nQ6, Q6	Output		Differential output pair. LVDS interface levels.

NOTE: Pullup and Pulldown refer to internal input resistors. See Table 2, Pin Characteristics, for typical values.

Low Skew, 1-to-16 DIFFERENTIAL-TO-LVDS CLOCK DISTRIBUTION CHIP

TABLE 2. PIN CHARACTERISTICS

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
C _{IN}	Input Capacitance			4		рF
R _{PULLUP}	Input Pullup Resistor			51		ΚΩ
R _{PULLDOWN}	Input Pulldown Resistor			51		ΚΩ
C _{PD}	Power Dissipation Capacitance (per output)			4		pF

TABLE 3A. CONTROL INPUT FUNCTION TABLE

Inputs Outputs					
OE1	OE2	Q0:Q7	nQ0:nQ7	Q8:Q15	nQ8:nQ15
0	0	Hi Z	Hi Z	Hi Z	Hi Z
1	0	ACTIVE	ACTIVE	Hi Z	Hi Z
0	1	Hi Z	Hi Z	ACTIVE	ACTIVE
1	1	ACTIVE	ACTIVE	ACTIVE	ACTIVE

In the active mode, the state of the outputs are a function of the CLK and nCLK inputs as described in Table 3B.

TABLE 3B. CLOCK INPUT FUNCTION TABLE

Inp	uts	Out	puts	Input to Output Mode	Polarity
CLK	nCLK	Q0:Q15	nQ0:nQ15		Polarity
0	1	LOW	HIGH	Differential to Differential	Non Inverting
1	0	HIGH	LOW	Differential to Differential	Non Inverting
0	Biased; NOTE 1	LOW	HIGH	Single Ended to Differential	Non Inverting
1	Biased; NOTE 1	HIGH	LOW	Single Ended to Differential	Non Inverting
Biased; NOTE 1	0	HIGH	LOW	Single Ended to Differential	Inverting
Biased; NOTE 1	1	LOW	HIGH	Single Ended to Differential	Inverting

NOTE 1: Please refer to the Application Information section, "Wiring the Differential Input to Accept Single Ended Levels".

Low Skew, 1-to-16 DIFFERENTIAL-TO-LVDS CLOCK DISTRIBUTION CHIP

ABSOLUTE MAXIMUM RATINGS

Supply Voltage, V_{DD} 4.6V

Inputs, V_{I} -0.5V to V_{DD} + 0.5 V

Outputs, $V_{\rm DD}$ + 0.5V to $V_{\rm DD}$ + 0.5V

Package Thermal Impedance, θ_{JA} 47.9°C/W (0 lfpm)

Storage Temperature, T_{STG} -65°C to 150°C

NOTE: Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These ratings are stress specifications only. Functional operation of product at these conditions or any conditions beyond those listed in the *DC Characteristics* or *AC Characteristics* is not implied. Exposure to absolute maximum rating conditions for extended periods may affect product reliability.

Table 4A. Power Supply DC Characteristics, $V_{DD} = 3.3V \pm 5\%$, $T_A = 0$ °C to 70°C

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
V _{DD}	Positive Supply Voltage		3.135	3.3	3.465	V
	Ctatia Dawar Cupply Current	$R_L = 100\Omega$		135	165	mA
I _{DD}	Static Power Supply Current	No Load		60	75	mA

Table 4B. LVCMOS/LVTTL DC Characteristics, $V_{DD} = 3.3V \pm 5\%$, $T_A = 0^{\circ}C$ to $70^{\circ}C$

Symbol	Parameter		Test Conditions	Minimum	Typical	Maximum	Units
V _{IH}	Input High Voltage	OE1, OE2		2		V _{DD} + 0.3	V
V _{IL}	Input Low Voltage	OE1, OE2		-0.3		0.8	V
I _{IH}	Input High Current	OE1, OE2	$V_{DD} = V_{IN} = 3.465V$			5	μΑ
I	Input Low Current	OE1, OE2	$V_{DD} = 3.465V, V_{IN} = 0V$	-150			μΑ

Table 4C. Differential DC Characteristics, $V_{DD} = 3.3V \pm 5\%$, $T_A = 0$ °C to 70°C

Symbol	Parameter		Test Conditions	Minimum	Typical	Maximum	Units
	Input High Current	CLK	$V_{IN} = V_{DD} = 3.465V$			150	μΑ
I _{IH}	Imput High Current	nCLK	$V_{IN} = V_{DD} = 3.465V$			5	μΑ
	Input Low Current	CLK	$V_{DD} = 3.465V, V_{IN} = 0V$	-5			μΑ
'IL	Imput Low Current	nCLK	$V_{DD} = 3.465V, V_{IN} = 0V$	-150			μΑ
V _{PP}	Peak-to-Peak Voltag	je		0.15		1.3	V
V _{CMR}	Common Mode Inpu NOTE 1, 2	ut Voltage;		GND + 0.5		V _{DD} - 0.85	V

NOTE 1: For single ended applications, the maximum input voltage for CLK, nCLK is V_{pp} + 0.3V.

NOTE 2: Common mode voltage is defined ast V_{IH}.

DIFFERENTIAL-TO-LVDS CLOCK DISTRIBUTION CHIP

Table 4D. LVDS DC Characteristics, $V_{DD} = 3.3V \pm 5\%$, Ta = 0°C to 70°C

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
V _{od}	Differential Output Voltage		250	400	600	mV
ΔV_{OD}	V _{op} Magnitude Change				50	mV
V _{os}	Offset Voltage		1.125	1.4	1.6	V
ΔV_{os}	V _{os} Magnitude Change				50	mV
l _{oz}	High Impedance Leakage Current		-10		+10	μΑ
I _{OFF}	Power Off Leakage		-1		+1	μΑ
I _{OSD}	Differential Output Short Circuit Current				-5.5	mA
I _{OS} /I _{OSB}	Output Short Circuit Current				-12	mA

Table 5. AC Characteristics, $V_{DD} = 3.3V \pm 5\%$, Ta = 0°C to 70°C

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
f _{MAX}	Output Frequency				700	MHz
t _{PD}	Propagation Delay; NOTE 1		1.6	2.0	2.4	ns
tsk(o)	Output Skew; NOTE 2, 4				90	ps
tsk(pp)	Part-to-Part Skew; NOTE 3, 4				500	ps
t _R /t _F	Output Rise/Fall Time	20% to 80%	100		550	ps
odc	Output Duty Cycle		45	50	55	%
t_{PZL}, t_{PZH}	Output Enable Time; NOTE 5				5	ns
t_{PLZ}, t_{PHZ}	Output Disable Time; NOTE 5				5	ns

NOTE 1: Measured from the differential input crossing point to the differential output crossing point.

NOTE 2: Defined as skew between outputs at the same supply voltages and with equal load conditions.

Measured at the output differential cross points.

NOTE 3: Defined as skew between outputs on different devices operating at the same supply voltages and with equal load conditions. Using the same type of inputs on each device, the outputs are measured at the differential cross points.

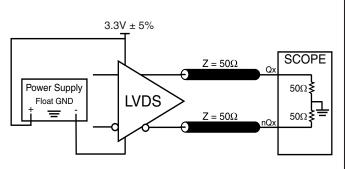
NOTE 4: This parameter is defined in accordance with JEDEC Standard 65.

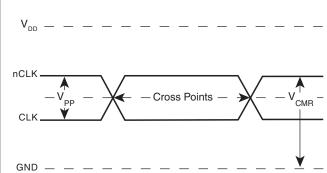
NOTE 5: These parameters are guaranteed by characterization. Not tested in production.

Low Skew, 1-TO-16

DIFFERENTIAL-TO-LVDS CLOCK DISTRIBUTION CHIP

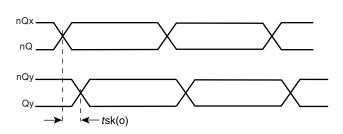
PARAMETER MEASUREMENT INFORMATION

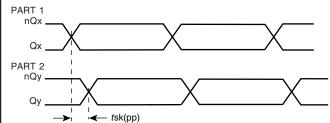




3.3V OUTPUT LOAD AC TEST CIRCUIT

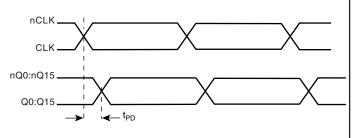
DIFFERENTIAL INPUT LEVEL

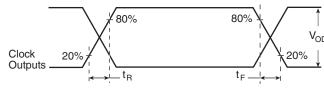




OUTPUT SKEW

PART-TO-PART SKEW

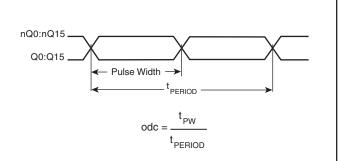


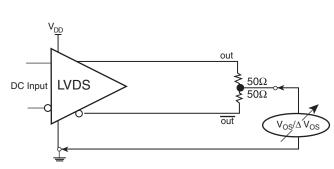


PROPAGATION DELAY

OUTPUT RISE/FALL TIME

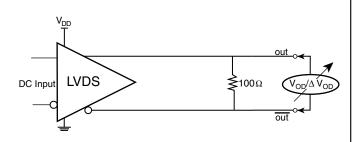
Low Skew, 1-to-16 DIFFERENTIAL-TO-LVDS CLOCK DISTRIBUTION CHIP

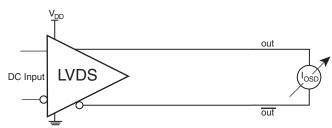




OUTPUT DUTY CYCLE/PULSE WIDTH/PERIOD

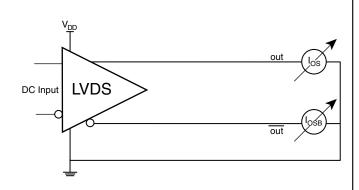
OFFSET VOLTAGE SETUP

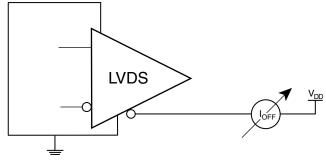




DIFFERENTIAL OUTPUT VOLTAGE SETUP

DIFFERENTIAL OUTPUT SHORT CIRCUIT CURRENT SETUP





OUTPUT SHORT CIRCUIT CURRENT SETUP

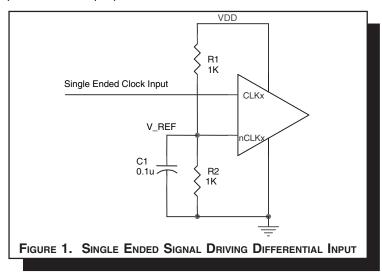
POWER OFF LEAKAGE SETUP

APPLICATION INFORMATION

WIRING THE DIFFERENTIAL INPUT TO ACCEPT SINGLE ENDED LEVELS

Figure 1 shows how the differential input can be wired to accept single ended levels. The reference voltage $V_REF = V_{DD}/2$ is generated by the bias resistors R1, R2 and C1. This bias circuit should be located as close as possible to the input pin. The ratio

of R1 and R2 might need to be adjusted to position the V_REF in the center of the input voltage swing. For example, if the input clock swing is only 2.5V and $V_{\rm DD}=3.3$ V, V_REF should be 1.25V and R2/R1 = 0.609.



LVDS DRIVER TERMINATION

A general LVDS interface is shown in Figure 2. In a 100 Ω differential transmission line environment, LVDS drivers require a matched load termination of 100 Ω across near the receiver in-

put. For a multiple LVDS outputs buffer, if only partial outputs are used, it is recommended to terminate the un-used outputs.

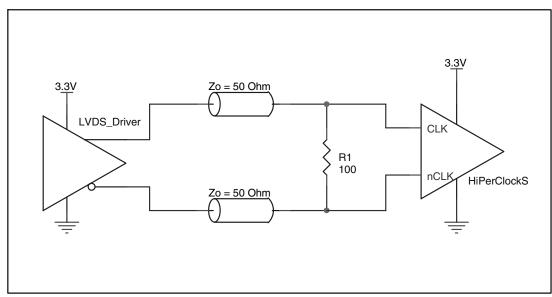


FIGURE 2. TYPICAL LVDS DRIVER TERMINATION



DIFFERENTIAL CLOCK INPUT INTERFACE

The CLK /nCLK accepts LVDS, LVPECL, LVHSTL, SSTL, HCSL and other differential signals. Both V_{SWING} and V_{OH} must meet the V_{PP} and V_{CMR} input requirements. Figures 3A to 3E show interface examples for the HiPerClockS CLK/nCLK input driven by the most common driver types. The input interfaces suggested

here are examples only. Please consult with the vendor of the driver component to confirm the driver termination requirements. For example in *Figure 3A*, the input termination applies for ICS HiPerClockS LVHSTL drivers. If you are using an LVHSTL driver from another vendor, use their termination recommendation.

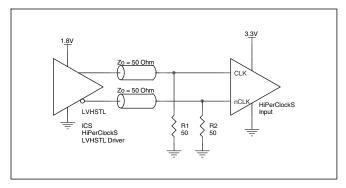


FIGURE 3A. HIPERCLOCKS CLK/nCLK INPUT DRIVEN BY ICS HIPERCLOCKS LVHSTL DRIVER

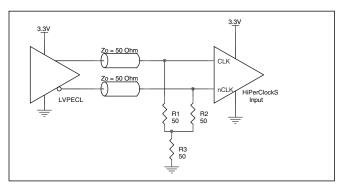


FIGURE 3B. HIPERCLOCKS CLK/nCLK INPUT DRIVEN BY 3.3V LVPECL DRIVER

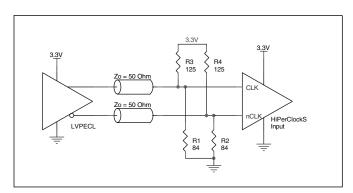


FIGURE 3C. HIPERCLOCKS CLK/nCLK INPUT DRIVEN BY 3.3V LVPECL DRIVER

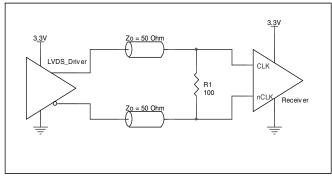


FIGURE 3D. HIPERCLOCKS CLK/nCLK INPUT DRIVEN BY 3.3V LVDS DRIVER

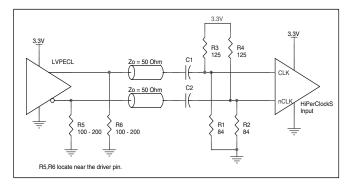


FIGURE 3E. HIPERCLOCKS CLK/NCLK INPUT DRIVEN BY 3.3V LVPECL DRIVER WITH AC COUPLE

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SCHEMATIC EXAMPLE

Figure 4 shows a schematic example of ICS8516. In this example, the input is driven by an LVDS driver. For LVDS buffer, it is recommended to terminate the unused outputs for better signal

integrity. The decoupling capacitors should be physically located near the power pin.

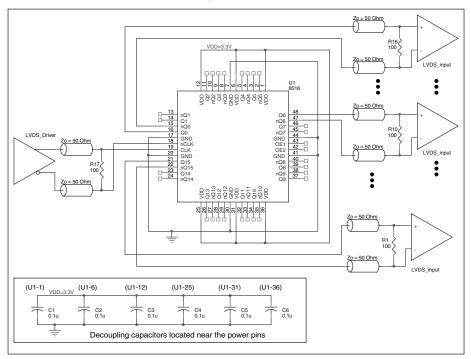


FIGURE 4. ICS8516 LVDS BUFFER SCHEMATIC EXAMPLE

RELIABILITY INFORMATION

θ₁, by Velocity (Linear Feet per Minute)

NOTE: Most modern PCB designs use multi-layered boards. The data in the second row pertains to most designs.

Table 6. $\theta_{\text{JA}} \text{vs. Air Flow Table for 48 Lead LQFP}$

	0	200	500
Single-Layer PCB, JEDEC Standard Test Boards	67.8°C/W	55.9°C/W	50.1°C/W
Multi-Layer PCB, JEDEC Standard Test Boards	47.9°C/W	42.1°C/W	39.4°C/W

TRANSISTOR COUNT

The transistor count for ICS8516 is: 1821



PACKAGE OUTLINE - Y SUFFIX FOR 48 LEAD LQFP

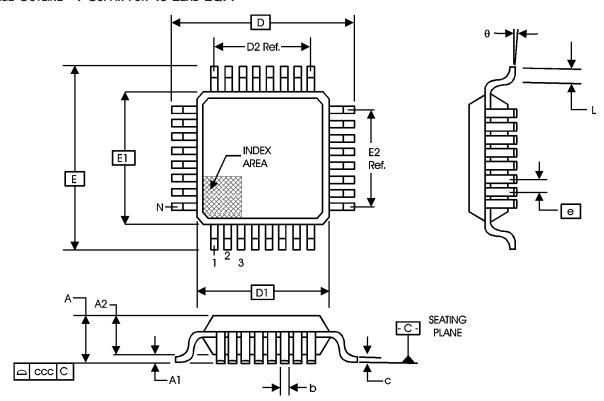


TABLE 7. PACKAGE DIMENSIONS

	JEDEC VARIATION ALL DIMENSIONS IN MILLIMETERS								
SYMBOL		BBC							
STWBOL	MINIMUM	NOMINAL	MAXIMUM						
N		48							
A			1.60						
A1	0.05		0.15						
A2	1.35	1.40	1.45						
b	0.17	0.17 0.22 0.27							
С	0.09		0.20						
D		9.00 BASIC							
D1		7.00 BASIC							
D2		5.50 Ref.							
E		9.00 BASIC							
E1		7.00 BASIC							
E2		5.50 Ref.							
е		0.50 BASIC							
L	0.45	0.60	0.75						
θ	0°		7°						
ccc			0.08						

Reference Document: JEDEC Publication 95, MS-026



Low Skew, 1-to-16 DIFFERENTIAL-TO-LVDS CLOCK DISTRIBUTION CHIP

TABLE 8. ORDERING INFORMATION

Part/Order Number	Marking	Package	Count	Temperature
ICS8516FY	ICS8516FY	48 Lead LQFP	250 per tray	0°C to 70°C
ICS8516FYT	ICS8516FY	48 Lead LQFP on Tape and Reel	1000	0°C to 70°C
ICS8516FYLF	ICS8516FYLF	48 Lead "Lead-Free" LQFP	250 per tray	0°C to 70°C
ICS8516FYLFT	ICS8516FYLF	48 Lead "Lead-Free" LQFP on Tape and Reel	1000	0°C to 70°C

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ICS8516 Low Skew, 1-to-16 DIFFERENTIAL-TO-LVDS CLOCK DISTRIBUTION CHIP

REVISION HISTORY SHEET				
Rev	Table	Page	Description of Change	Date
А	T1	2	Pin Description table - added pins 47 thru 48.	3/31/03
		8	Added LVDS Driver Termination in the Application Information section.	
Α	T1	2	Pin Description Table - switched pin names for 45, 46 & 47,48	5/6/03
А	T2	3	Pin Characteristics Table - changed C _{IN} from 4pF max. to 4pF typical.	
		9	Updated Differential Clock Input Interface section.	7/30/04
	T8	12	Ordering Information Table - added Lead-Free part numbers.	